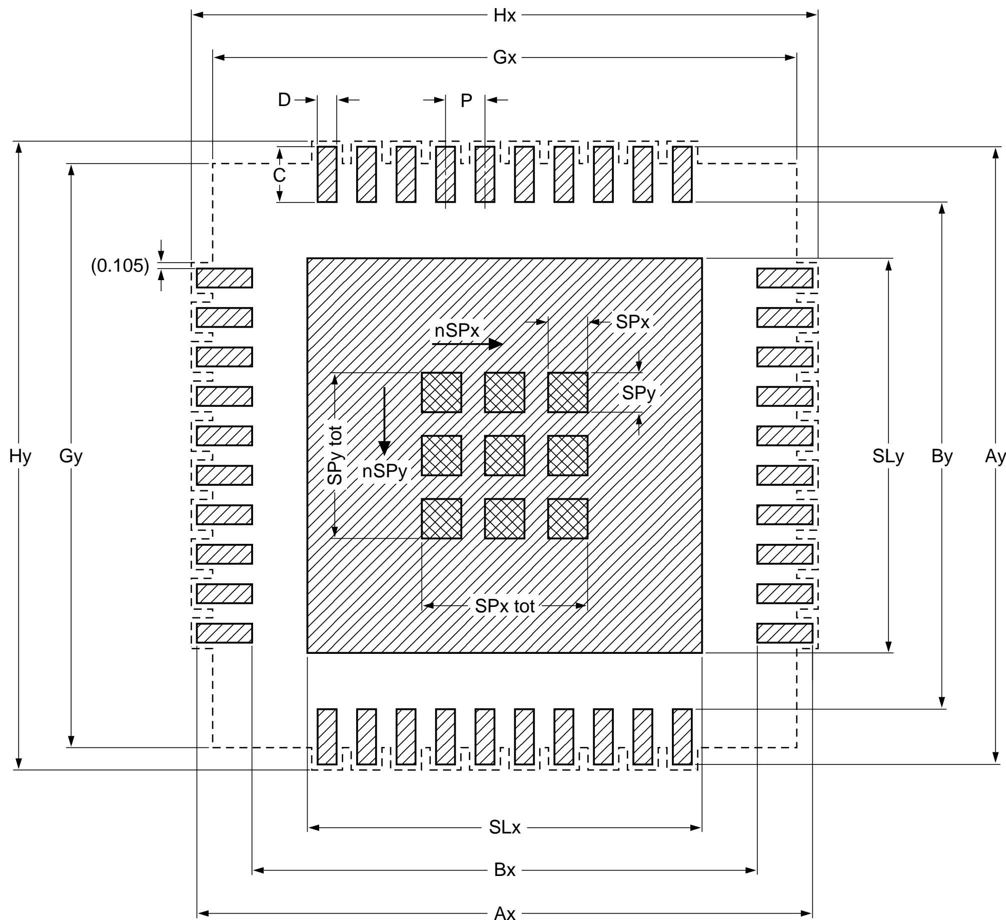
Footprint information for reflow soldering of HVQFN16 package **SOT758-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

solder paste deposit

solder land plus solder paste

occupied area

nSPx	nSPy
1	1

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	4.000	4.000	2.200	2.200	0.900	0.240	1.500	1.500	0.650	0.650	0.650	0.650	3.300	3.300	4.250	4.250

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